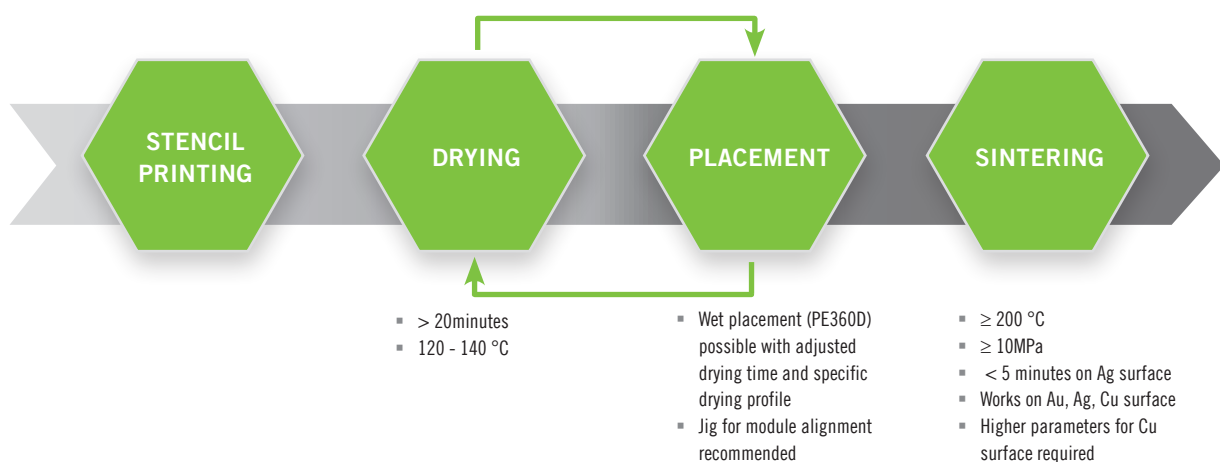


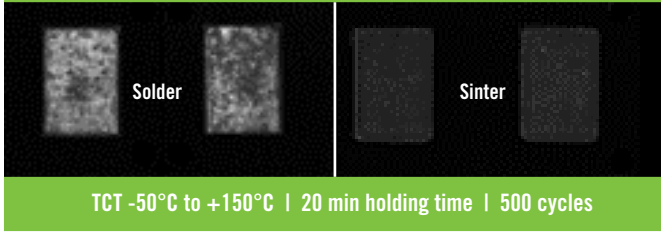


mAgic® PE360 Pressure Silver Sinter Paste for Module Attach Applications

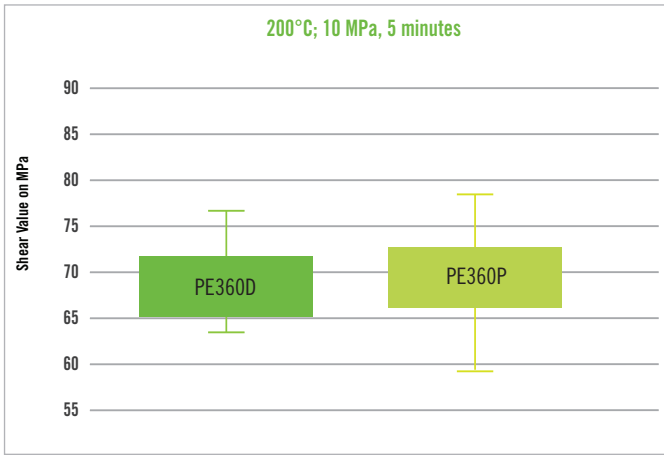
PE360 is a pressure sinter paste developed for module attach applications. It comes in two different versions. PE360P is suitable for the stencil printing and dry module placement and PE360D works for dispensing and wet-/dry-placement process. Both offer excellent thermal performance, achieved with fast process times and for the application optimized workability.



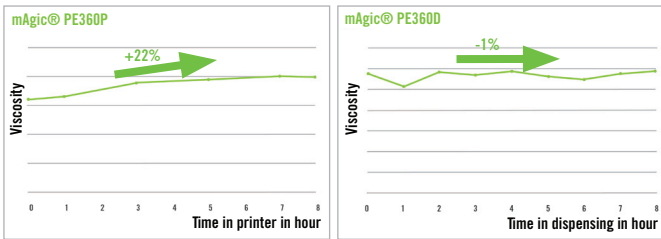
Superior Reliability under Harsh Conditions



Shear Value on ~220mm²



Excellent Long Term Paste Workability for Printing and Dispensing Application



- Excellent printing performance overtime
- Consistent paste deposit volume for high production efficiency
- Stable rheology for long stencil life

Product Properties	PE360P	PE360D
Alloy	Silver	
Metal Content	87% +/- 1%	
Fillers	0%	
Particle Size	≤ 25 μm	
Sinter Temperature	≥ 200°C	
Halogen Content	Halogen Zero	
Compatible Surfaces	Au, Ag, Cu	
Sinter Atmosphere	Air/N ₂	
Application Process	PE360P	PE360D
Printing	Yes	No
Dispensing	No	Yes
Features and Benefits	PE360P	PE360D
Work Life	8 hours	
Shelf Life	6 months	3 months
Residue Cleaning	Not required	
Storage Condition	-18 to -22°C	
Shipping Condition	2 to 10°C	

Americas

Phone 1 610 825 6050
electronics.americas@heraeus.com

Asia Pacific

Phone +65 6571 7649
electronics.apac@heraeus.com

China

Phone +86 53 5815 9601
electronics.china@heraeus.com

Europe, Middle East and Africa

Phone +49 6181 35 4370
electronics.emea@heraeus.com

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